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Jan. 9, 2005  
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Docket No.: F0361.C1.D1

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Steven C. Avanzino, et al. : Confirmation No.: 7845  
Serial No.: 10/608,883 : Art Unit: 2813  
Filed: 6/26/2003 : Examiner: Stephen W. Smoot  
For: INTEGRATED CIRCUIT :  
WITH DIELECTRIC  
DIFFUSION BARRIER  
LAYER FORMED  
BETWEEN  
INTERCONNECTS AND  
INTERLAYER DIELECTRIC  
LAYERS

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RESPONSE /AMENDMENT AFTER FINAL REJECTION  
UNDER 37 C.F.R. §1.116

Sir:

The following Amendment and Remarks are submitted under 37 C.F.R. §1.116 in response to the Office Action mailed 11/10/2004, following the amendment format set forth under 37 CFR §1.121. After this introductory section, there are Amendments to the Specification and then Remarks, each starting on a separate page.

The Cross Reference to Related Applications section of the Specification has been amended to correct the serial number of the priority application.